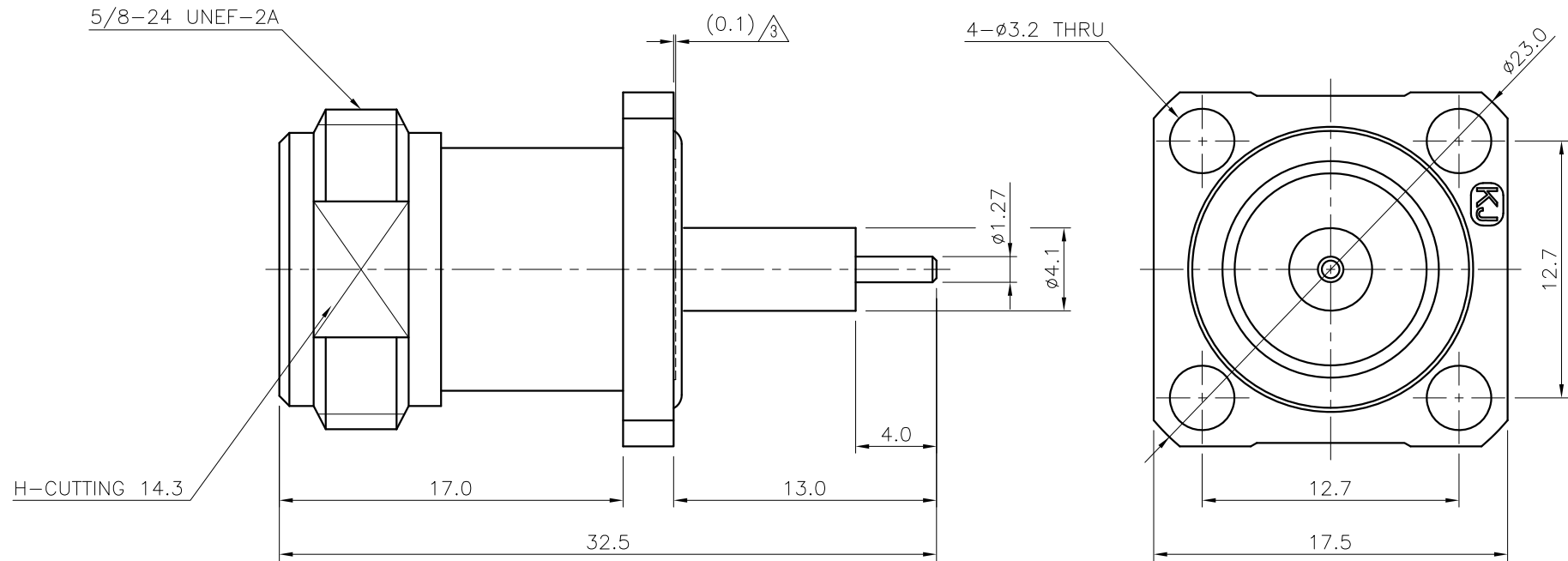


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM		2016.08.02.
1	[설변No.201907-0003] NBR -> SILICONE 재질 변경	S.Y.EUN	I.C.KIM	2019.07.02.
2	[설변No.202012-0002] O-RING 빠짐 개선 안착부 금형수정	I.C.KIM		2020.12.07.
3	[설변No.202101-0003] O-RING 빠짐 개선 안착부 0.1mm Ground Boss 추가	S.Y.EUN	I.C.KIM	2021.01.20.
4	RING 억지끼움후 돌출부위 감안하여 길이 조정	S.H.KIM		2024.11.08.



5	RING	1	MBsBD C3604BD-F	Nickel Plate	DSR01097-5/4 DSR01097-5/3
4	INSULATOR	1	TEFLON		DIN02813-N/1
3	GASKET	1	SILICONE NBR		DGK00257-N/2 DGK00257-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03741-5/1
1	BODY	1	ZnDC	Nickel Plate (3~4μm)	DBD02992-5/3 DBD02992-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 11. 08.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY			
MATERIAL _____		CHECKED BY	TITLE N50 SOLDER END JS-4H		
		DRAWN BY			
FINISH _____		SCALE 3/1	UNIT mm	 A4	DWG NO. CN03958-7/2
					REVISION 4